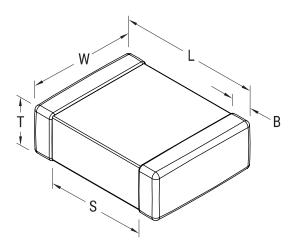


C0805C473M3GECTU

mm

Aliases (C0805C473M3GEC7800) ESD SMD Comm C0G, Ceramic, 0.047 uF, 20%, 25 VDC, C0G, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 0805, 0.7



Click here for the 3D model.

General Information	
Series	ESD SMD Comm COG
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	14 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	0805
L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
т	1.25mm +/-0.15mm
S	0.7mm MIN
В	0.5mm +/-0.25mm

Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	2500

Specifications	
Capacitance	0.047 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	20%
Voltage DC	25 VDC
ESD Level per AEC-Q200	25,000 V ESD Level
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	21.2766 GOhms

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